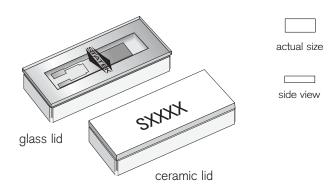


CX1SM AT CRYSTAL

8 MHz to 250 MHz

Miniature Surface Mount AT Quartz Crystal

Fundamental Mode: 8 MHz - 250 MHz Third Overtone Mode: 48 MHz - 160 MHz



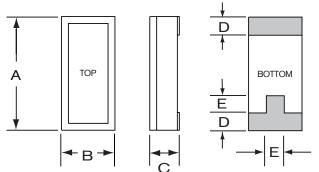
DESCRIPTION

STATEK's miniature CX1SM AT crystals in leadless ceramic packages are designed for surface mounting on printed circuit boards or hybrid substrates. Due to its robust design, this product has gained wide acceptance in the industry.

FEATURES

- Designed for surface mount applications using infrared, vapor phase, or epoxy mount techniques
- Low profile hermetically sealed ceramic package
- Excellent aging characteristics
- Available with glass or ceramic lid
- High shock and vibration resistance
- Custom designs available
- Full military testing available
- Designed and manufactured in the USA

PACKAGE DIMENSIONS



APPLICATIONS

Medical

- Infusion Pumps
- Monitoring Equipment

Industrial, Computer & Communications

- Instrumentation
- Process Control
- Environmental Control
- Telemetry

Military & Aerospace

- Communications
- Satellite Command and Control
- Cockpit Electronics
- Smart Munitions
- Timing Devices (Fuzes)

	TYPICAL		MAXIMUM		
DIM	inches	mm	inches	mm	
Α	0.315	8.00	0.330	8.38	
В	0.140	3.56	0.155	3.94	
С	-	-	see below		
D	0.045	1.14	0.055	1.40	
Е	0.060	1.52	0.070	1.78	

THICKNESS (DIM C) MAXIMUM

	GLASS LID		CERAMIC LID	
	inches	mm	inches	mm
SM1	0.065	1.65	0.070	1.78
SM2/SM4	0.067	1.70	0.072	1.83
SM3/SM5	0.070	1.78	0.075	1.90

10107 - Rev B



SPECIFICATIONS

Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice.

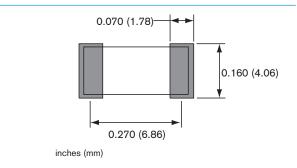
Specifications are subject to change without notice.				
Fundamental Frequency	<u>10 MHz</u>	32 MHz	<u>155.52 MHz</u>	
Motional Resistance R_1 (Ω)	30	25	15	
Motional Capacitance C_1 (fF)	5.5	6.2	4.0	
Quality Factor Q (k)	100	30	30	
Shunt Capacitance C_0 (pF)	2.2	2.3	2.3	
Calibration Tolerance ¹	± 100 pp	m, or tighte	er as required	
Load Capacitance ²	20 pF for	f ≤ 50 MH	·lz	
	10 pF for	f > 50 MH	Hz	
Drive Level	500 μW I	MAX for f	≤ 50 MHz	
	200 μW I	MAX for f	> 50 MHz	
Frequency-Temperature Stability ^{1,3}	± 100 pp	m to ± 20	ppm (Commercial) opm (Industrial) opm (Military)	
Aging, first year4	5 ppm M	AX (better th	an 1ppm available)	
hock, survival ⁵ 3,000 g, 0.3 ms, 1/2 sine		2 sine		
Vibration, survival ⁶	20 g, 10-	2,000 Hz s	swept sine	
Operating Temp. Range	-40°C to -	+70°C (Co +85°C (In +125°C (M		
Storage Temp. Range	-55°C to -	+125°C		

TERMINATIONS

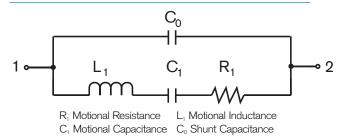
<u>Designation</u>	<u>Termination</u>
SM1	Gold Plated (Lead Free)
SM2	Solder Plated
SM3	Solder Dipped
SM4	Solder Plated (Lead Free)
SM5	Solder Dipped (Lead Free)

Max Process Temperature 260°C for 20 sec.

SUGGESTED LAND PATTERN



EQUIVALENT CIRCUIT



 $1. \ Other \ tolerances \ available. \ Contact \ factory.$

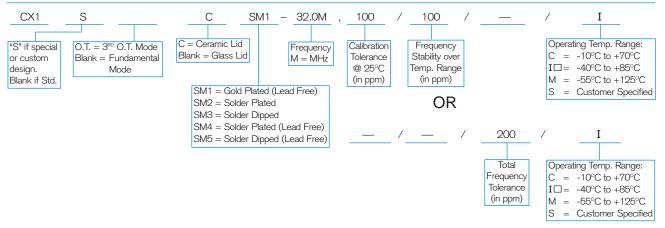
Max Process Temperature 260°C for 20 sec.

- 2. Unless specified otherwise.
- 3. Does not include calibration tolerance. The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.
- 5 ppm MAX for frequencies below 40 MHz. For tighter tolerances and higher frequencies contact factory.
- 5. Higher shock version available. Refer to data sheet model CX1HGSM AT (10108).
- 6. Per MIL-STD-202G, Method 204D, Condition D. Random vibration testing also available.

PACKAGING OPTIONS

- Tray Pack
- 16mm tape, 7" or 13" reels
 Per EIA 481 (see Tape and Reel data sheet 10109)

HOW TO ORDER CX1SM AT CRYSTALS



10107 - Rev B

